



Notes:

1. All dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed thermal pad as well as the terminals.
3. Refer JEDEC MO-137 AE
4. Recommended land pattern is for reference only.
5. Thermal pad soldering area (mesh stencil design is recommended).



DATE: 10/05/10

DESCRIPTION: 56-Pin, Thin Fine Pitch Quad Flat No-lead, TQFN

PACKAGE CODE: ZB (ZB56)

DOCUMENT CONTROL #: PD-2008

REVISION: G